



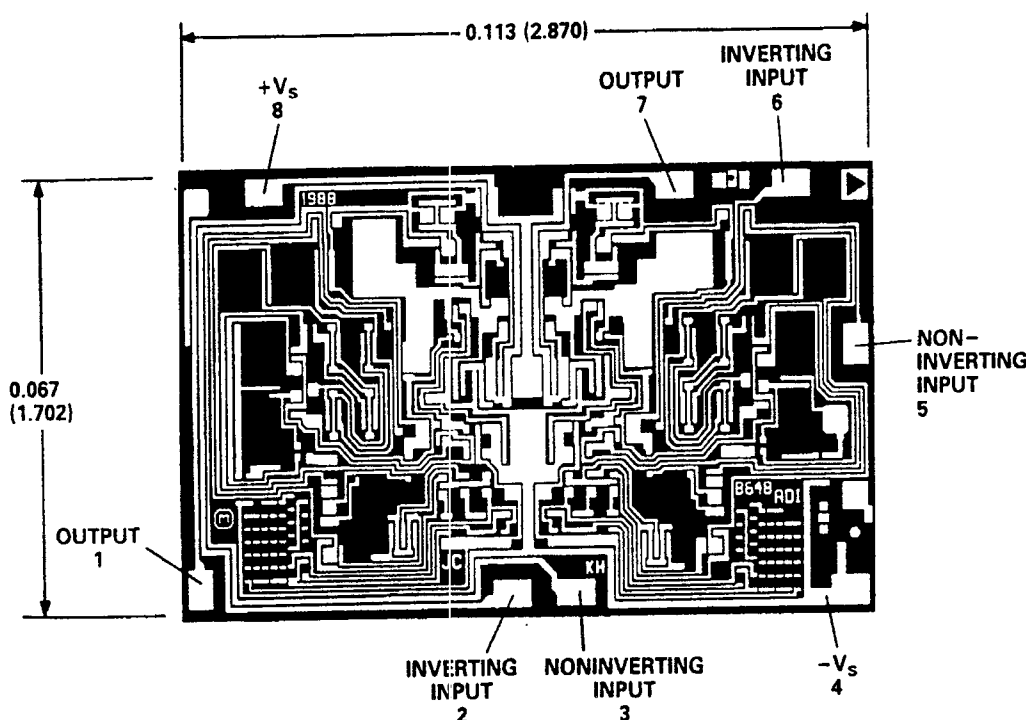
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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

METALIZATION PHOTOGRAPH

Contact factory for latest dimensions.
 Dimensions shown in inches and (mm).



Topside Metal:
Backside:
Backside Potential:
Mask Ref:
Bond Pads (Mils):

APPROVED BY:
MFG: Analog Devices

DIE SIZE (Mils): 113 X 67
THICKNESS:

DATE: 3/2/00
P/N: AD648